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FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	ONFIRMATION NO.	
08/04/2000	Kohei Tatsumi	52433/609	1969	
90 09/30/2002	•	•		
KENYON				
VAY		EXAMINER		
IY 10004		CHAMBLISS	IAMBLISS, ALONZO	
		ART UNIT	PAPER NUMBER	
		2827		
		DATE MAILED: 09/30/2002		
	08/04/2000 · 90 09/30/2002 KENYON /AY	08/04/2000 Kohei Tatsumi 90 09/30/2002 KENYON	08/04/2000 Kohei Tatsumi 52433/609 90 09/30/2002 KENYON /AY Y 10004 EXAMI	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	am
Advisory Action	09/632,910	TATSUMI ET AL.	
The state of the s	Examiner	Art Unit	
	Alonzo Chambliss	2027	
The MAILING DATE of this communication	appears on the cover sheet w	ith the correspondence and	
THE REPLY FILED FAILS TO PLACE THIS Therefore, further action by the applicant is required final rejection under 37 CFR 1.113 may only be eith condition for allowance; (2) a timely filed Notice of A Examination (RCE) in compliance with 37 CFR 1.11	APPLICATION IN CONDITION to avoid abandonment of this er: (1) a timely filed amendment	N FOR ALLOWANCE.	h. to
PERIOD FO	R REPLY (check either a) or b	7) 7	
a) ine period for reply expires 5 months from the mailing	amalaka den erika i		
no event, however, will the statutory period for reply e ONLY CHECK THIS BOX WHEN THE FIRST REPLY 706.07(f). Extensions of time may be obtained under 37 CFR 1.136(a) see have been filed is the date for purposes of determining the period of the control of the c	f this Advisory Action, or (2) the date expire later than SIX MONTHS from the WAS FILED WITHIN TWO MONTH. The date on which the petition undersided of extension and the correspondiate of the shortened statutory period for	S OF THE FINAL REJECTION. or 37 CFR 1.136(a) and the approxing amount of the fee. The approxing amount of the fee.	on. See MPEP opriate extension
I. A Notice of Appeal was filed on Appeal	anto Print months of the man		ction, even if
37 CFR 1.192(a), or any extension thereof (37 ∴ The proposed amendment(s) will not be entered	OF IN 1. 19 HOLL TO AVOID DISMI	ssal of the appeal.	
(a) They raise new issues that would be entered	ed because:		
(a) they raise new issues that would require for	urther consideration and/or sea	arch (see NOTE below);	
 (b) ☐ they raise the issue of new matter (see No (c) ☒ they are not deemed to place the applications issues for appeal; and/or 	ote below); on in better form for appeal by	materially reducing or sim	nolifying the
(d) they present additional claims without can			
Applicant's reply has overcome the following rej	ection(s):		
Newly proposed or amended claim(s) wo canceling the non-allowable claim(s).	uld be allowable if submitted in	n a separate, timely filed a	mendment
☐ The a)☐ affidavit, b)☐ exhibit, or c)☐ request application in condition for allowance because:			
The affidavit or exhibit will NOT be considered by raised by the Examiner in the final rejection.	pecause it is not directed SOLE		
For purposes of Appeal, the proposed amendment explanation of how the new or amended claims	would be rejected is provided	or b) will be entered and	d an
The status of the claim(s) is (or will be) as follow	rs:		
Claim(ş) allowed:	<u>f</u>	KAMAND CUNEO	
Claim(s) objected to:	, Su	PERVISORY PATENT EXAMIN	MED
Claim(s) rejected: <u>16-26</u> .		TECHNOLOGY CENTER 2800) Ven
Claim(s) withdrawn from consideration:			-
The proposed drawing correction filed on	is a) approved on b)	•••••••••••••••	
Note the attached Information Disclosure Statem	ent(e)(DTO 1440) D	approved by the Examiner	r.
☑ Other: <u>See Continuation Sheet</u>	اداسرعرر ۱۵-۱449) Paper No(s	S)	
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Continuation of 10. Other: As mention in the Final rejection, Juskey discloses that the solder bumps can be used with a chip carrier or other members that are well known in the art. One skilled in the art would readily recognize that a semiconductor chip would be considered as an other member, since a semiconductor chip is formed from a wafer substrate that has been sliced into individual chips. Thus, the electrodes as claimed by the applicant can be formed on the chip in the manner as taught by Juskey. Furthermore, Juskey discloses a flip chip connection, since the solder blow is first attached to the chip by reflow that is readily recognize to one skilled in the art and then flip to a position that is seen in Fig. 3